

Dual N-Channel 30V (D-S) MOSFET

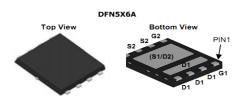
PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A)	Q _g (Typ.)			
30	0.0034 at V _{GS} = 10 V	60	17 nC			
	0.0043 at V_{GS} = 4.5 V	55				

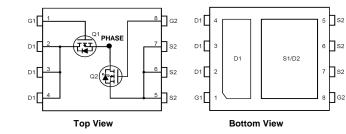
FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- TrenchFET[®] Power MOSFET
- 100 % UIS Tested
- 100 % Rg Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- Set Top Box
- Low Current DC/DC





Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	30	V	
Gate-Source Voltage		V _{GS}	± 20	v	
Continuous Drain Current (T _J = 150 °C)	T _C = 25 °C T _C = 70 °C	-	60 ^a 50		
	T _A = 25 °C	I _D	25.2 ^{b, c}		
Pulsed Drain Current T _A = 70 °C		I _{DM}	22.2 ^{b, c} 200	Α	
Continuous Source-Drain Diode Current	T _C = 25 °C T _A = 25 °C	I _S	2.25 1.48 ^{b, c}		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	5		
Single Pulse Avalanche Energy		E _{AS}	1.25	mJ	
Maximum Power Dissipation	$T_{C} = 25 \text{ °C}$ $T_{C} = 70 \text{ °C}$	P _D	56 15		
	T _A = 25 °C T _A = 70 °C		2.18 ^{b, c} 1.34 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c, d}	t ≤ 10 s	R _{thJA}	58	70	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	38	45		

Notes:

a. Package limited, $T_C = 25 \ ^{\circ}C$.

b. Surface Mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. Maximum under Steady State conditions is 110 °C/W.

COMPLIANT HALOGEN

FREE



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static			•			1	
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$	30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	1 250 4		32		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 5.0			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	1.0		2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1	1	
		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			10	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 V, V_{GS} = 10 V$	10			А	
		V _{GS} = 10 V, I _D = 5 A		0.0034			
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 4 \text{ A}$		0.0043		Ω	
Forward Transconductance ^a	g _{fs}	$V_{DS} = 10 \text{ V}, I_D = 5 \text{ A}$		16		S	
Dynamic ^b	1 -10 1						
Input Capacitance	C _{iss}			1300			
Output Capacitance	C _{oss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz		257		pF	
Reverse Transfer Capacitance	C _{rss}			155			
Total Gate Charge	Q _g	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 5 \text{ A}$		17		nC	
				3.7	5.6		
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 5 \text{ A}$		1.4			
Gate-Drain Charge	Q _{gd}			1.05			
Gate Resistance	R _g	f = 1 MHz	0.8	4.3	8.6	Ω	
Turn-On Delay Time	t _{d(on)}			12	24	ns	
Rise Time	t _r	$V_{DD} = 15 \text{ V}, \text{ R}_{1} = 3 \Omega$		55	100		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		11	22		
Fall Time	t _f			8	16		
Turn-On Delay Time	t _{d(on)}			4	8		
Rise Time	t _r	$V_{DD} = 15 V, R_1 = 3 \Omega$		9	18		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 5 \text{ A}, V_{GEN} = 10 \text{ V}, \text{ R}_g = 1 \Omega$		10	20		
Fall Time	t _f	-		6	12		
Drain-Source Body Diode Characteristi	cs						
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			2.25		
Pulse Diode Forward Current	I _{SM}				24	A	
Body Diode Voltage	V _{SD}	I _S = 2 A, V _{GS} = 0 V		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}		1	11	20	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			4	8	nC	
Reverse Recovery Fall Time	ta	$I_F = 5 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, \text{T}_J = 25 \text{ °C}$		7			
Reverse Recovery Rise Time	t _b			4		ns	

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %

b. Guaranteed by design, not subject to production testing.

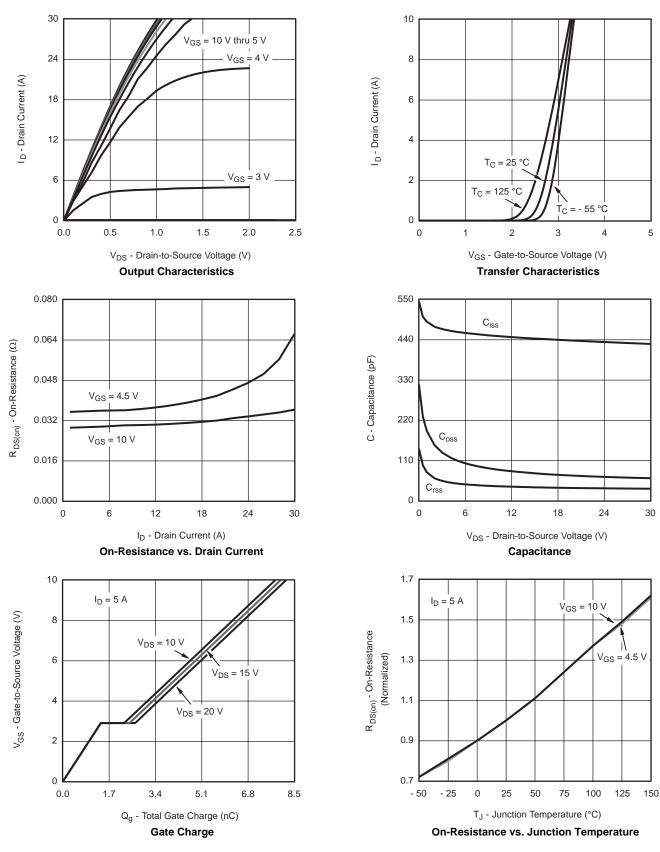
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



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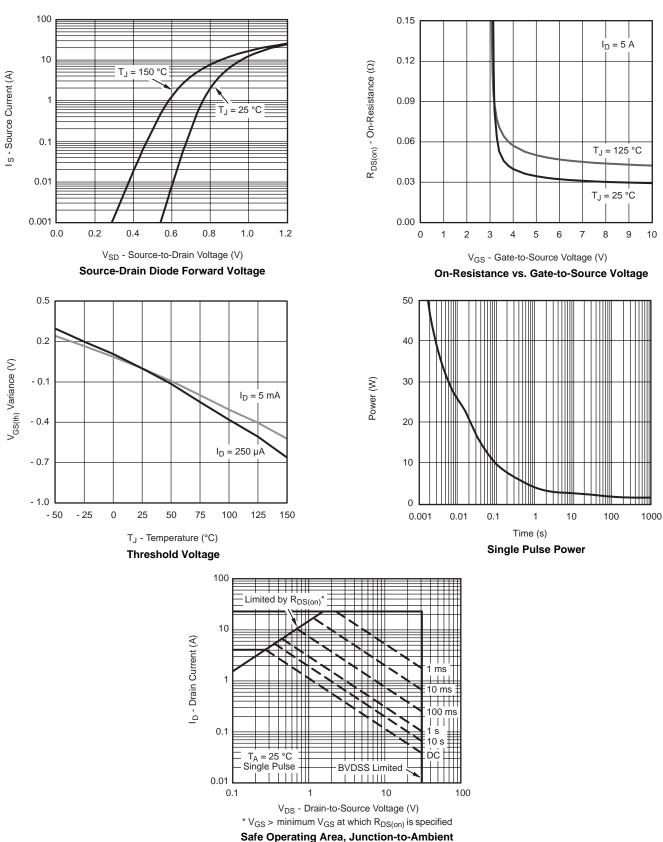
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



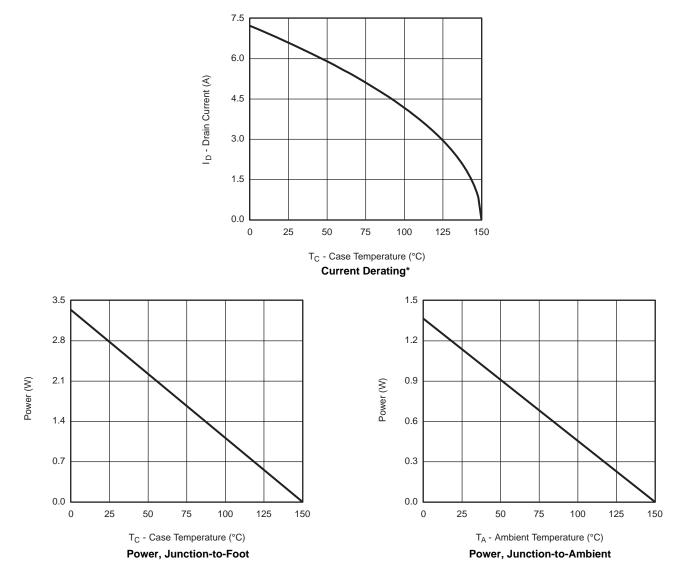








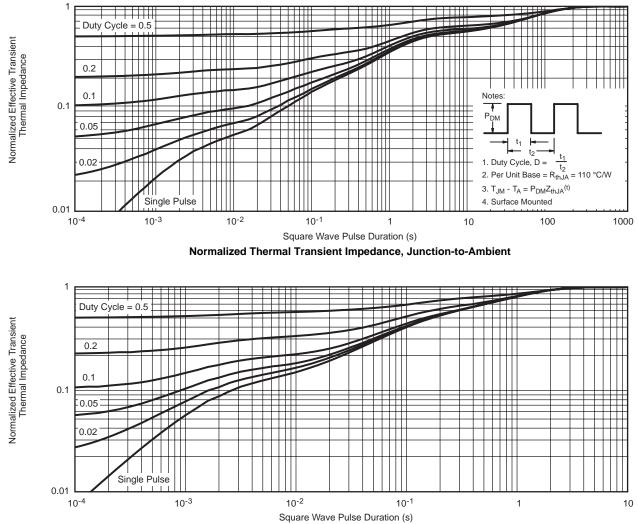
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* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Foot



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